

**GENERAL DESCRIPTION**

This Trench MOSFET has better characteristics, such as fast switching time, low on resistance, low gate charge and excellent avalanche characteristics. It is mainly suitable for portable equipment and SMPS.

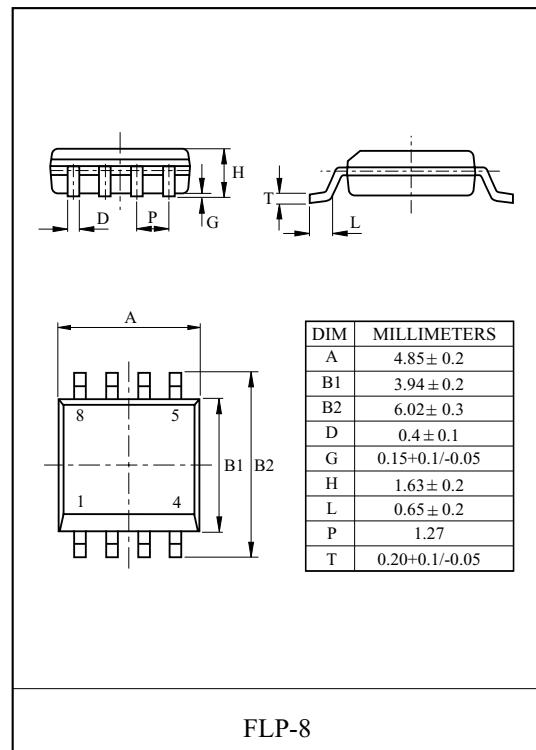
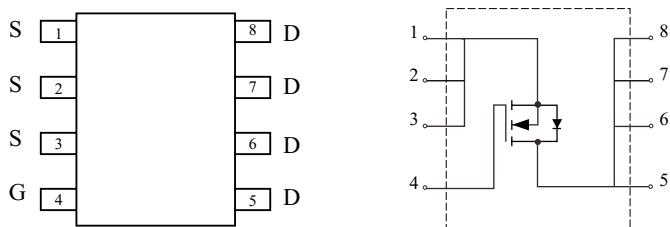
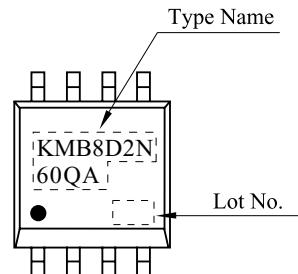
**FEATURES**

- $V_{DSS}=60V$ ,  $I_D=8.2A$ .
- Drain-Source ON Resistance.  
 $R_{DS(ON)}=22m\Omega$  (Max.) @  $V_{GS}=10V$   
 $R_{DS(ON)}=27m\Omega$  (Max.) @  $V_{GS}=4.5V$
- Super High Dense Cell Design

**MOSFET Maximum Ratings (Ta=25 °C Unless otherwise noted)**

CHARACTERISTIC	SYMBOL	PATING	UNIT
Drain Source Voltage	$V_{DSS}$	60	V
Gate Source Voltage	$V_{GSS}$	$\pm 25$	V
Drain Current	$I_D$ *	8.2	A
		6.6	A
	$I_{DP}$	40	A
Drain Source Diode Forward Current	$I_S$	3.0	A
Drain Power Dissipation	$P_D$ *	3.0	W
		2.0	W
Maximum Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C
Thermal Resistance, Junction to Ambient	$R_{thJA}$ *	41	°C/W

Note : \*Surface Mounted on 1 × 1 FR4 Board

**PIN CONNECTION (TOP VIEW)****Marking**

# KMB8D2N60QA

## ELECTRICAL CHARACTERISTICS (Ta=25°C) UNLESS OTHERWISE NOTED

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	-	-	V
Drain Cut-off Current	I <sub>DSS</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V	-	-	1	μA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>j</sub> =70 °C	-	-	5	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>th</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	-	3.0	V
Drain-Source ON Resistance	R <sub>DS(ON)*</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =8.2A	-	16	22	m Ω
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =7.6A	-	20	27	
Forward Transconductance	G <sub>fs*</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =8.2A	-	2.4	-	S
<b>Dynamic</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz	-	1920	2300	pF
Output Capacitance	C <sub>oss</sub>		-	155	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	116	-	
Total Gate Charge (V <sub>GS</sub> =10V)	Q <sub>g*</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =8.2A	-	47.6	58	nC
Total Gate Charge (V <sub>GS</sub> =4.5V)			-	24.2	30	
Gate-Source Charge	Q <sub>gs*</sub>		-	6.0	-	
Gate-Drain Charge	Q <sub>gd*</sub>		-	14.4	-	
Turn-On Delay Time	t <sub>d(on)*</sub>	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V R <sub>L</sub> =3.6 Ω, R <sub>G</sub> =3 Ω	-	8.2	-	ns
Turn-On Rise Time	t <sub>r*</sub>		-	5.5	-	
Turn-On Delay Time	t <sub>d(off)*</sub>		-	29.7	-	
Turn-On Fall Time	t <sub>f*</sub>		-	5.2	-	
<b>Source-Drain Diode Ratings</b>						
Source-Drain Forward Voltage	V <sub>SDF*</sub>	V <sub>GS</sub> =0V, I <sub>DR</sub> =1.7A,	-	0.74	1.0	V
Note						
1. Pulse Test : Pulse width ≤ 10μs , Duty cycle ≤ 1%						

# KMB8D2N60QA

Fig1.  $I_D$  -  $V_{DS}$

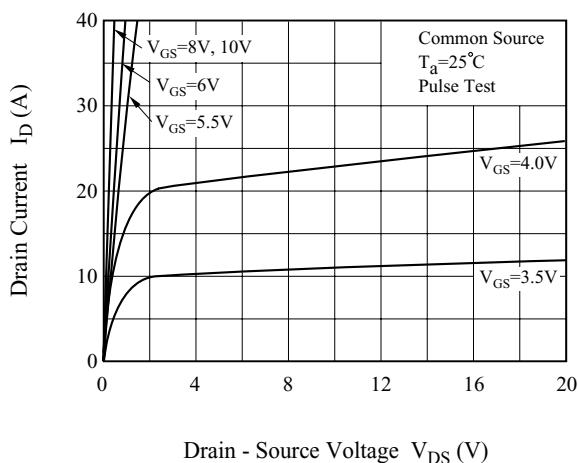


Fig2.  $R_{DS(ON)}$  -  $I_D$

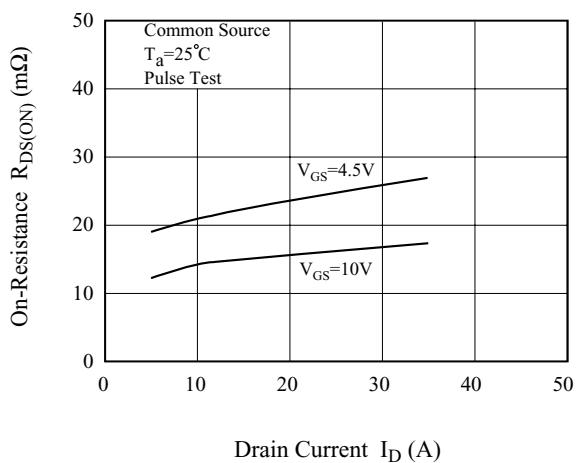


Fig3.  $I_D$  -  $V_{GS}$

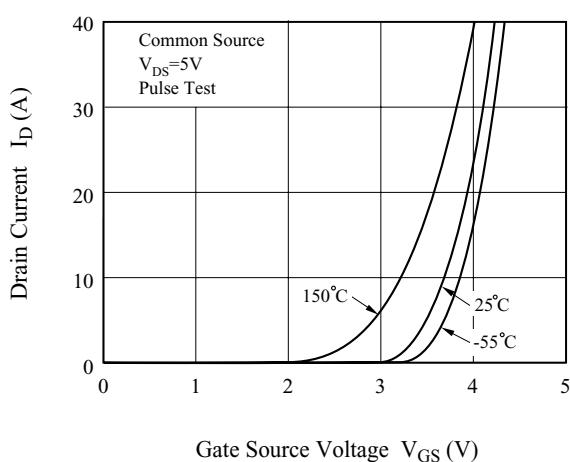


Fig4.  $R_{DS(ON)}$  -  $T_j$

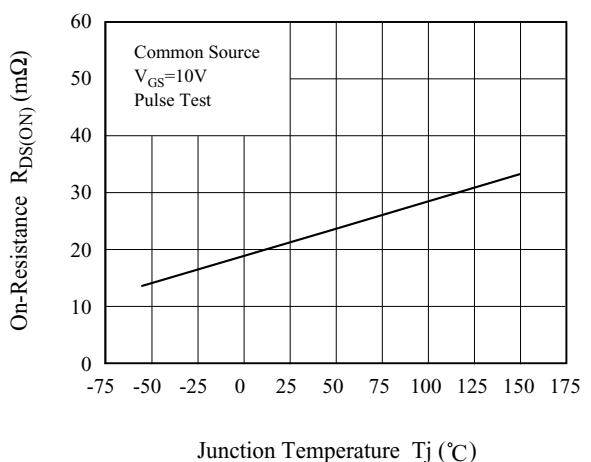


Fig5.  $V_{th}$  -  $T_j$

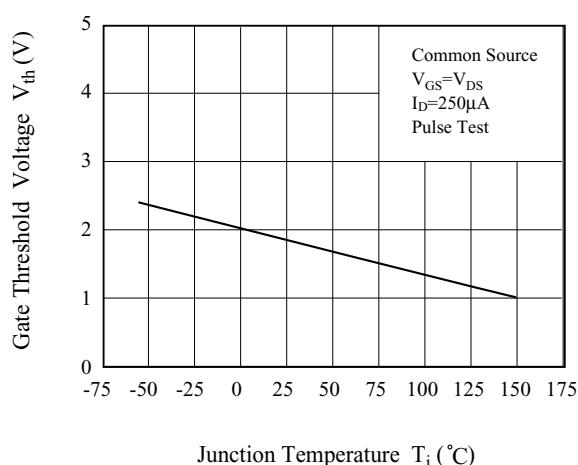
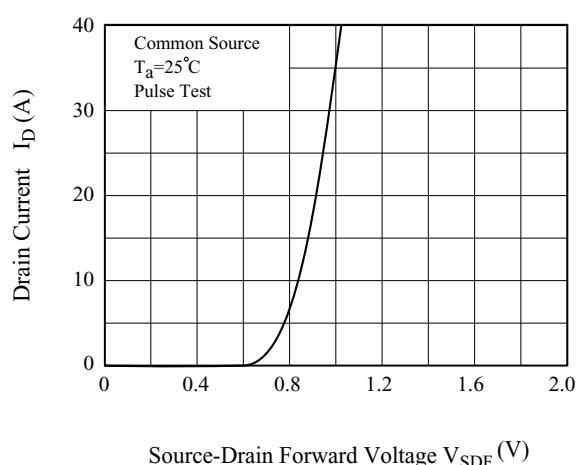


Fig 6.  $I_S$  -  $V_{SDF}$



# KMB8D2N60QA

Fig7.  $V_{GS}$  -  $Q_g$

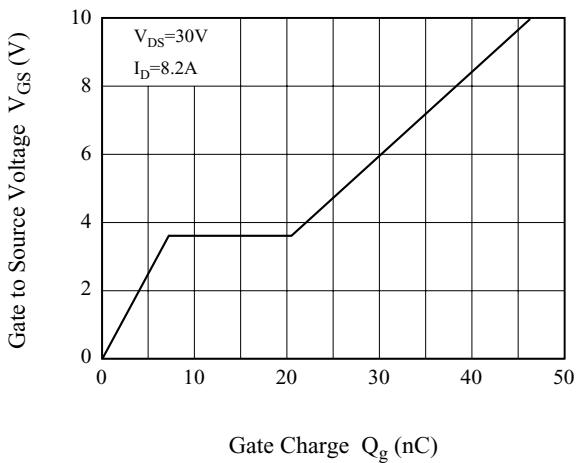


Fig8. C -  $V_{DS}$

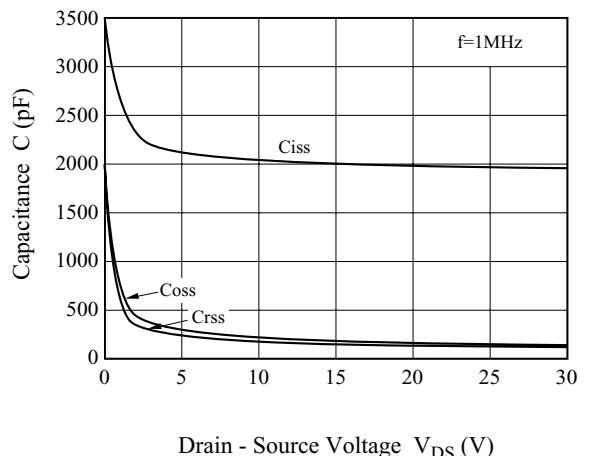


Fig9. Safe Operation Area

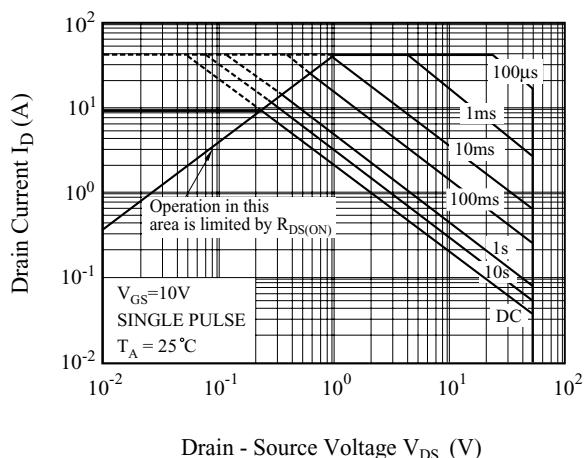


Fig10. Transient Thermal Response Curve

